

PICOSECOND INFRARED LASER

P-ir-30 Series

30W

Picosecond IR Laser



Laser wavelength

1064nm

Pulse Width

<10ps

Pulse-to-Pulse Stability

<2%rms

Application

Products of this series are specifically designed for High precision marking and cutting of glass, Drilling and cutting of sapphire Marking, drilling and cutting of ceramics, Cutting of LCD/OLED display panels, Scribing and cutting of LED wafers

PARAMETER	INDEX	DESCRIPTION
Wavelength	1064nm	
Output Power	$\geq 30W@1MHz$	Maximum output power 40W@1MHz
Pulse Width	<10ps	
Power Stability	<2% rms	(8hrs)
Beam Quality	TEM00($M^2 < 1.3$)	
Pointing Stability	20urad/ $^{\circ}C$	
Repetition Rate	300kHz-1500KHz	Can be customized
Beam Divergence Angle	<3mrad	Full angle
Beam Circularity	>90%	
Beam Diameter	$1.5 \pm 0.3\text{mm}$	
Polarization Ratio	100:1	
Cooling Method	Water-cooling	
Power Supply Requirements	AC: 200-240V, 7.5A, 50/60Hz	
Total Power Consumption	<600W	
Laser Operation Mode	Avg. Power output 0%-100% tunable; burst mode; PoD(pulse of demand)	
Environmental Humidity Requirements	< 80%	
Cooling Capacity of Chiller	$\geq 1000W$	
Chiller Temperature Setting	20 $^{\circ}C$	

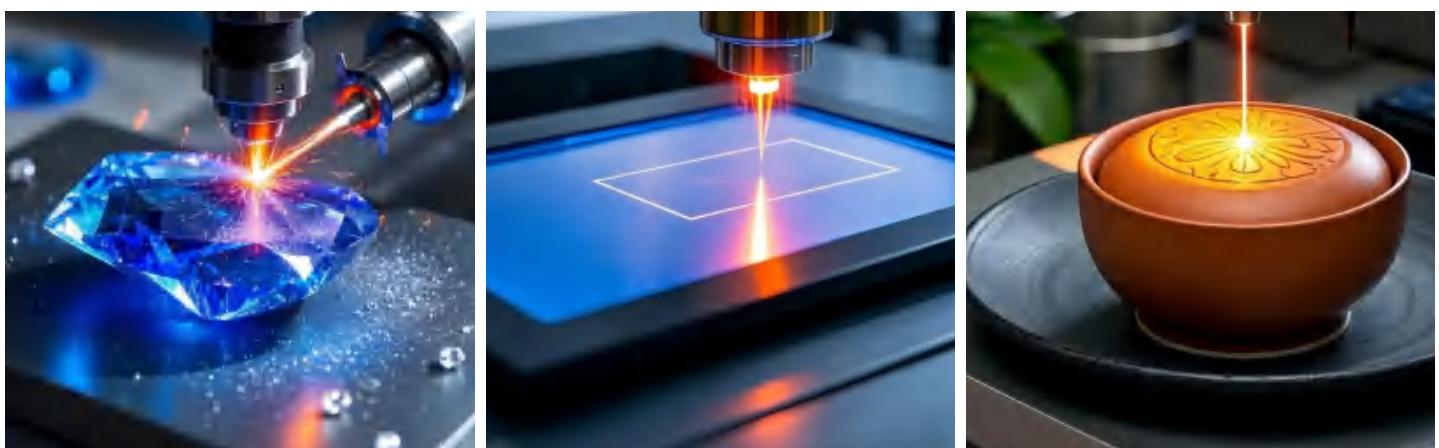
Laser power and other characteristics can be optimized in different repetition frequency ranges;
The temperature referred to is the ambient temperature.



- Fiber-solid hybrid MOPA technology, ensuring high reliability;
- Laser pulse width <10ps, maximum single pulse energy >100 μ J;
- Burst Mode control circuit, offering more process possibilities and higher processing efficiency;
- Different Gate and PWM signal combination trigger modes, achieving Burst, PSO, POD functions;
- Customers can achieve continuous laser output power adjustment from 0-100% through external control analog voltage.
- The laser can be controlled in real-time through a handheld device;
- Real-time monitoring of the laser's operating temperature, high-temperature alarm system ensuring safe operation of the laser;
- Quick switching function for laser parameters, enabling processing with different process parameters on multiple layers.



Glass Marking



Sapphire Cutting

LCD Cutting

Ceramic Marking



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